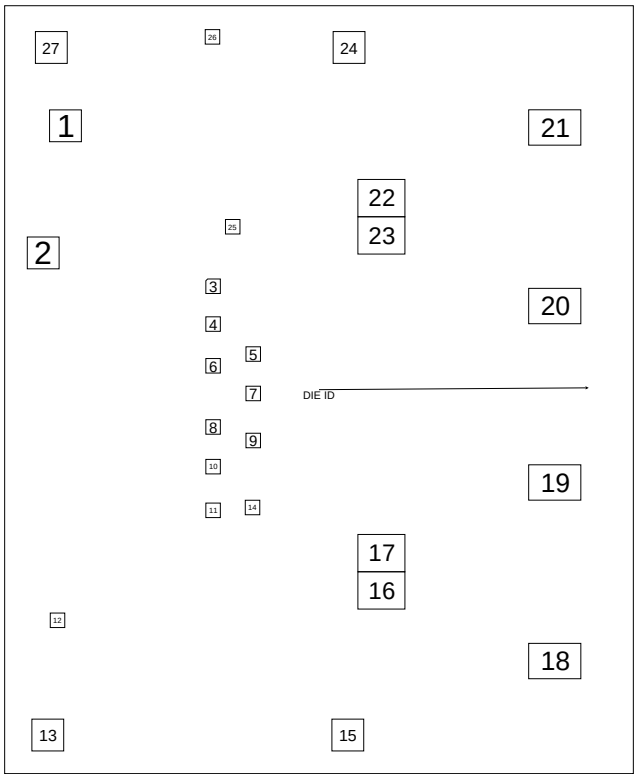
LM2588-5.0-MWC
SIMPLE SWITCHER 5A Flyback Regulator with Shutdown

26-Jul-2013

DIE LAYOUT (E-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM1587E-5.0	Bond Pad Opening Size (min)	180.00µm x 180.00µm
Die Step	E	Bond Pad Metalization	0.5%CU
Physical Attributes		Passivation	PECVDOX NITRIDE
Wafer Diameter	200mm	Back Side Metal	TINIAG
Die Size (Drawn)	3556.000µm x 4343.400µm 140.0mils x 171.0mils	Back Side Connection	Floating
Thickness	330.2µm Nominal		
Min Pitch	450.17µm		
Note: All values are rounded to the nearest micron.			
Special Assembly Requirements:			

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Die Bond Pad Coordinate Locations(E-Step)
(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X		Y
Feedback	1	-1434.00	1492.50	180.00	x	180.00
GND	2	-1560.00	773.50	180.00	x	180.00
NC	3	-599.00	585.00	82.00	x	82.00
NC	4	-599.00	371.00	82.00	x	82.00
NC	5	-372.00	201.50	82.00	x	82.00
NC	6	-599.00	135.00	82.00	x	82.00
NC	7	-372.00	-21.50	82.00	x	82.00
NC	8	-599.00	-211.00	82.00	x	82.00
NC	9	-372.00	-287.50	82.00	x	82.00
NC	10	-599.00	-435.50	82.00	x	82.00
NC	11	-599.00	-682.50	82.00	x	82.00
NC	12	-1479.00	-1304.50	82.00	x	82.00
Freq. Sync.	13	-1534.00	-1953.50	180.00	x	180.00
NC	14	-376.00	-666.50	82.00	x	82.00
Vin	15	163.00	-1953.50	180.00	x	180.00
Switch	16	353.00	-1135.50	266.00	x	211.00
Switch	17	353.00	-924.50	266.00	x	211.00
GND	18	1333.50	-1535.00	295.00	x	200.00
GND	19	1333.50	-525.00	295.00	x	200.00
GND	20	1333.50	473.00	295.00	x	200.00
GND	21	1333.50	1483.00	295.00	x	200.00
Switch	22	353.00	1083.50	266.00	x	211.00
Switch	23	353.00	872.50	266.00	x	211.00
Freq. Adj. -- On/Off	24	170.00	1935.50	180.00	x	180.00
NC	25	-488.00	921.50	82.00	x	82.00
NC	26	-602.50	1995.50	82.00	x	82.00
Compensation	27	-1514.00	1935.50	180.00	x	180.00

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Notes

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